Anirudha Behera

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SUMMARY

I am a passionate Physical Design Engineer with 1+ years of experience in ASIC design flow, specializing in PnR, STA, and low-power design techniques. Proficient in RTL to GDSII implementation and optimization using Synopsys and Cadence tools. Experienced in resolving design challenges and improving PPA metrics across advanced nodes.

EDUCATION

Illinois Institute of Technology, Chicago, USA

01/2022 - 12/2023

Master of Science in Electrical Engineering

GPA: 3.53/4.0

Relevant Courses: Introduction to VLSI, CAD Techniques for VLSI Design, High-Performance

VLSI/IC Systems, Digital SoC Design, Computer Organization and Design, RF Integrated Circuit Design

Gandhi Institute For Technology, Bhubaneswar, India

08/2014 - 07/2018

Bachelor of Technology in Electrical Engineering

GPA: 8.1/10

Department Rank 1 (5th - 8th Semester), Recipient of the Best Live Major Project Team Award in 2018 **SKILLS**

Programming Languages: Perl, TCL Methodology, Bash Shell, Basics of Python, Verilog HDL

EDA Tools: Synopsys ICC2, Design Compiler, PrimeTime, Star RC, IC Validator, Cadence Virtuoso, Encounter, Calibre, ModelSim, Innovus, Redhawk

Physical Design Processes: Floorplan, Power Plan, Placement, Routing, CTS, STA, DRC/LVS, ECO, UPF, RC Extraction, DFT, SDC/Timing Constraint

WORK EXPERIENCE

Honorex Technologies, Washington, USA

05/2024 - Present

Physical Design Engineer for Marvell Semiconductor

- Contributed to the Place and Route (PnR) flow for AI accelerators and high-performance processors targeting 3nm node, optimizing for timing, power, and area (PPA) across multiple process corners (MCMM). The designs involved over 5M+ standard cells and 62 macros, targeting a frequency of 1.8 GHz.
- Performed Static Timing Analysis (STA) for complex designs, identifying and resolving timing violations to ensure that **clock frequencies** met **performance** and **power** requirements for Marvell's **custom processors**.
- Developed and optimized TCL scripts to automate key tasks in the PnR and STA processes, reducing iteration cycles and increasing design efficiency, while maintaining high accuracy in Design Rule Checks (DRC) and Layout Versus Schematic (LVS).
- Collaborated with cross-functional teams in design, verification, and manufacturing to ensure design integrity and achieve closure timing, contributing to the successful tape-out of advanced AI and data center processors.
- Utilized industry-standard EDA tools to address design challenges, including IR-drop and crosstalk issues, and ensured that the **design integrity** was maintained at sign-off, focusing on **robust performance** across varying operating conditions.

Design Automation LAB, IIT, Chicago, USA

08/2023 - 12/2023

- Research Assistant
- Dedicated 500+ hours working with EDA tools under Dr. Ken Choi executing the RTL-to-GDSII flow for 14nm and 28nm TSMC nodes using Synopsys Design Compiler and ICC2, developing a tailored methodology for efficient floorplan and Power Delivery Network (PDN) design, optimizing IR-drop resilience and power delivery efficiency.
- Enhanced QOR by minimizing post-Powerplan shorts, improving power grid robustness, and ensuring design scalability and integrity across MMMC and RC corners through rigorous validation.

ChipEdge Technology, Bengaluru, India

10/2022 - 07/2023

Physical Design Apprenticeship

- Managed physical design phases including Logic Synthesis, Floorplan, Placement, CTS, Routing, and Optimization to meet Power, Performance, and Area (PPA) targets across 14nm, 22nm, 32nm, and 45nm nodes using TSMC FinFET/CMOS technology.
- Resolved STA violations for designs up to 2M cells and 80+ macros, ensuring compliance with timing and power requirements through thorough analysis and optimization.
- Achieved successful GDSII tape-outs by addressing DRC, LVS, ERC, IREM, and Logic Equivalence (LEC) issues, leveraging Shell scripting and TCL methodology for ECO cycles, manual debugging, and automation.

ACADEMIC PROJECTS

OpenSPARC T1 Block Level design from RTL to GDSII using 14nm and 28nm TSMC nodes | DC | ICC2

02/2023

- 75% core-area utilization and density sweeps were used to understand congestion and routability behavior.
- Optimized design using insertion and size cell techniques to eliminate DRVs like Caps and Trans. [https://github.com]